



PART B - FEE(S) TRANSMITTAL

Complete and send this form, together with applicable fee(s) to: Mail

Mail Stop ISSUE FEE
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450
FAX (571) 273-2885

INSTRUCTIONS: This form should be used for transmitting the ISSUE FEE and PUBLICATION FEE (if required). Blocks 1 through 5 should be completed where appropriate. All further correspondence including the Patent, advance orders and notification of maintenance fees will be mailed to the current correspondence address as indicated unless corrected below or directed otherwise in Block 1, by (a) specifying a new correspondence address; and/or (b) indicating a separate "FEE ADDRESS" for maintenance fee notifications.

CURRENT CORRESPONDENCE ADDRESS (Note: Use Block 1 for any change of address)

23494 7590 12/5/2005

TEXAS INSTRUMENTS INCORPORATED
PO BOX 655474, M/S 3999
DALLAS, TX 75265
05/17/2006 HDEMESS2 00000089 200668 10797779

01 FC:1501 1400.00 DA
 02 FC:1504 300.00 DA

Note: A certificate of mailing can only be used for domestic mailings of the Fee(s) Transmittal. This certificate cannot be used for any other accompanying papers. Each additional paper, such as an assignment or formal drawings, must have its own certificate of mailing or transmission.

CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this Fee(s) Transmittal is being deposited with the United States Postal Service with sufficient postage for first class mail in an envelope addressed to the Mail Stop ISSUE FEE address above, or being facsimile transmitted to the USPTO, on the date indicated below.

Karen Vertz	(Depositor's name)
/Karen Vertz/ Karen Vertz	(Signature)
May 17, 2006	(Date)

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/797,779	03/09/04	Kejun Zeng	TI-36626	4149

TITLE OF INVENTION: METHOD OF SEMICONDUCTOR DEVICE ASSEMBLY INCLUDING FATIGUE-RESISTANT TERNARY SOLDER ALLOY

APPLN. TYPE	SMALL ENTITY	ISSUE FEE	PUBLICATION FEE	TOTAL FEE(S) DUE	DATE DUE
nonprovisional	NO	\$1,400	\$300	\$1,700	07/24/2006

EXAMINER	ART UNIT	CLASS-SUBCLASS
EDMONDSON, LYNNE RENEE	1725	228-248100

1. Change of correspondence address or indication of "Fee Address" (37 CFR 1.363).
 Change of correspondence address (or Change of Correspondence Address form PTO/SB/122) attached.
 "Fee Address" indication (or "Fee Address" Indication form PTO/SB/47; Rev. 03-02 or more recent) attached. Use of a Customer Number is required.

2. For printing on the patent front page, list
 (1) the names of up to 3 registered patent attorneys or agents OR, alternatively,
 (2) the name of a single firm (having as a member a registered attorney or agent) and the names of up to 2 registered patent attorneys or agents. If no name is listed, no name will be printed.

1 W. James Brady, III
 2 Frederick J. Telecky, Jr.
 3 _____

3. ASSIGNEE NAME AND RESIDENCE DATA TO BE PRINTED ON THE PATENT (print or type)

PLEASE NOTE: Unless an assignee is identified below, no assignee data will appear on the patent. If an assignee is identified below, the document has been filed for recordation as set forth in 37 CFR 3.11. Completion of this form is NOT a substitute for filing an assignment.

(B) RESIDENCE: (CITY and STATE OR COUNTRY)

(A) NAME OF ASSIGNEE

PO BOX 655474, M/S 3999
 DALLAS, TX 75265

Please check the appropriate assignee category or categories (will not be printed on the patent) individual corporation or other private group entity government

4a. The following fee(s) are enclosed:
 Issue Fee
 Publication Fee (No small entity discount permitted)
 Advance Order - # of Copies _____

4b. Payment of Fee(s):
 A check in the amount of the fee(s) is enclosed.
 Payment by credit card. Form PTO-2038 is attached.
 The Director is hereby authorized to charge the required fee(s), or credit any overpayment, to Deposit Account Number 20-0668 (enclose an extra copy of this form).

5. Change in Entity Status (from status indicated below)
 a. Applicant claims SMALL ENTITY status. See 37 CFR 1.27.
 b. Applicant is no longer claiming SMALL ENTITY status. See 37 CFR 1.27(g)(2).

The Director of the USPTO is requested to apply the Issue Fee and Publication Fee (if any) or to re-apply any previously paid issue fee to the application identified above.

NOTE: The Issue Fee and Publication Fee (if required) will not be accepted from anyone other than the application; a registered attorney or agent; or the assignee or other party in interest as shown by the records of the United States Patent and Trademark Office

Authorized Signature

Date 15 May 2006

Typed or printed name

Gary C. Honeycutt

Registration No. 20,250

This collection of information is required by 37 CFR 1.311. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, PO Box 1450, Alexandria, Virginia 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, PO Box 1450, Alexandria, Virginia 22313-1450.

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

TRANSMIT THIS FORM WITH FEE(S)



Facsimile Number: 571-273-2885

Total Pages Sent 2

From:

Texas Instruments Incorporated
Facsimile: 972-917-4418

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Kejun Zeng

Docket Number: TI-36626

Serial No.: 10/797,779

Art Unit: 1725

Filed: 03/09/04

Examiner: Lynne R. Edmondson

For: Method of Semiconductor Device Assembly Including
Fatigue-Resistant Ternary Solder Alloy

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile
to the U.S. Patent and Trademark Office on the date shown below:

Karen Vertz
Karen Vertz

5-17-06
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input type="checkbox"/> AMENDMENT (# pages)
<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT
<input type="checkbox"/> DECLARATION	<input type="checkbox"/> NOTICE OF APPEAL
<input type="checkbox"/> ASSIGNMENT	<input type="checkbox"/> APPEAL (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS	<input checked="" type="checkbox"/> ISSUE FEE & PUBLICATION FEE (1 Page)
<input type="checkbox"/> INFORMAL DRAWINGS	<input type="checkbox"/> REPLY BRIEF (IN TRIPPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APP'N	<input type="checkbox"/> ELECTION
<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S):	
Kejun Zeng	
RECEIPT DATE & SERIAL NO.:	
Serial No.: 10/797,779	
Filing Date: 03/09/04	
TITLE OF INVENTION: Method of Semiconductor Device Assembly Including Fatigue-Resistant Ternary Solder Alloy	
TI FILE NO.:	DEPOSIT ACCT. NO.:
TI-36626	20-0668
FAXED: 5-17-06	
DUE: 7-24-06	
ATTY/SECY: GCH/kjv	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265-5474